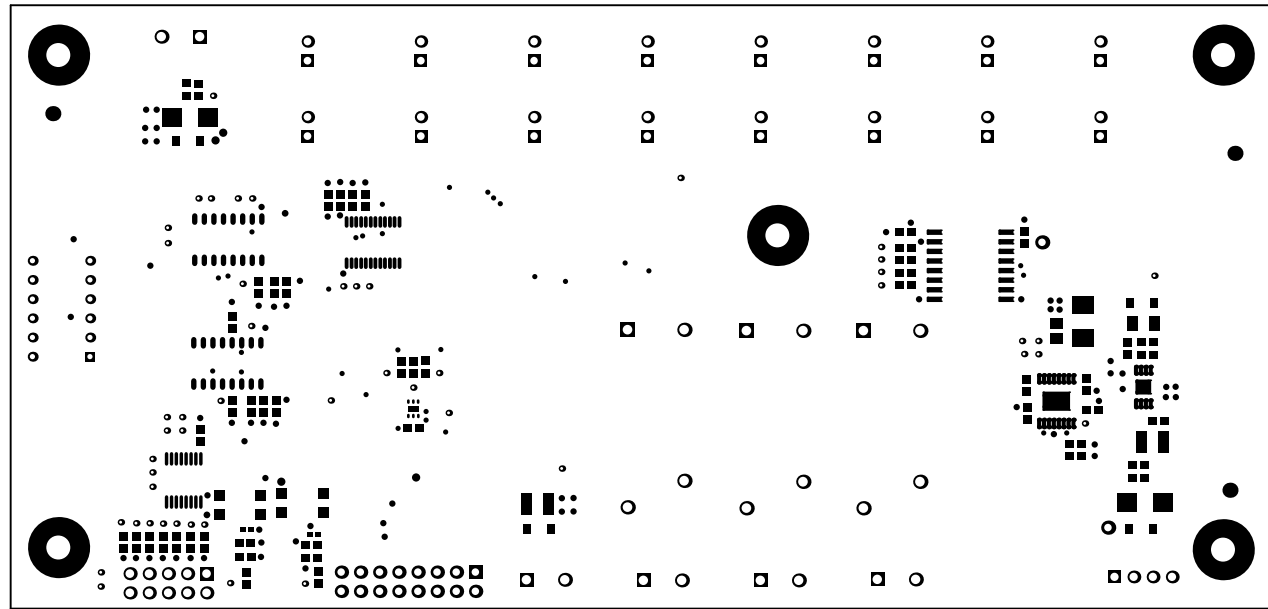
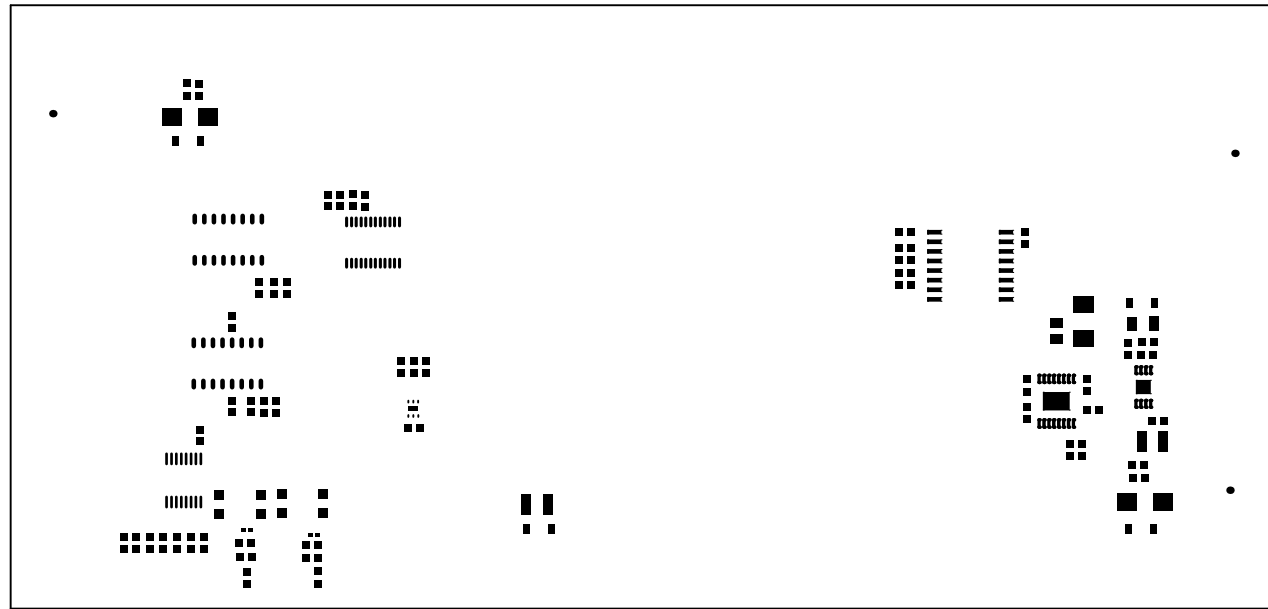


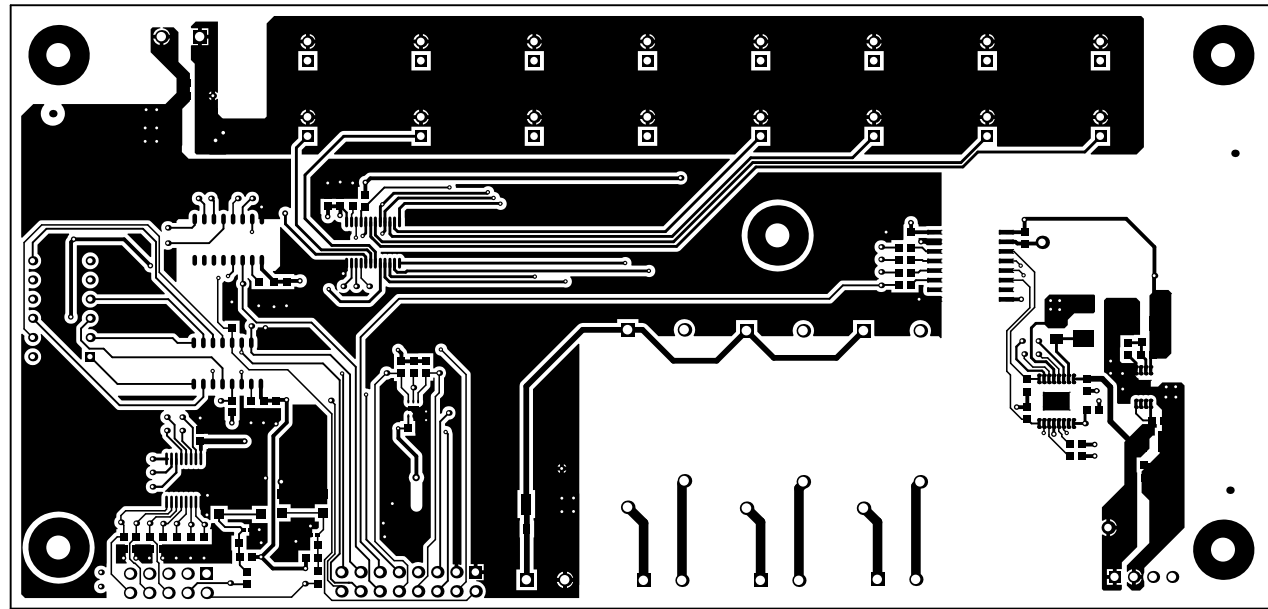
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00737	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 11/30/2015 4:21:06 PM	TEXAS INSTRUMENTS	



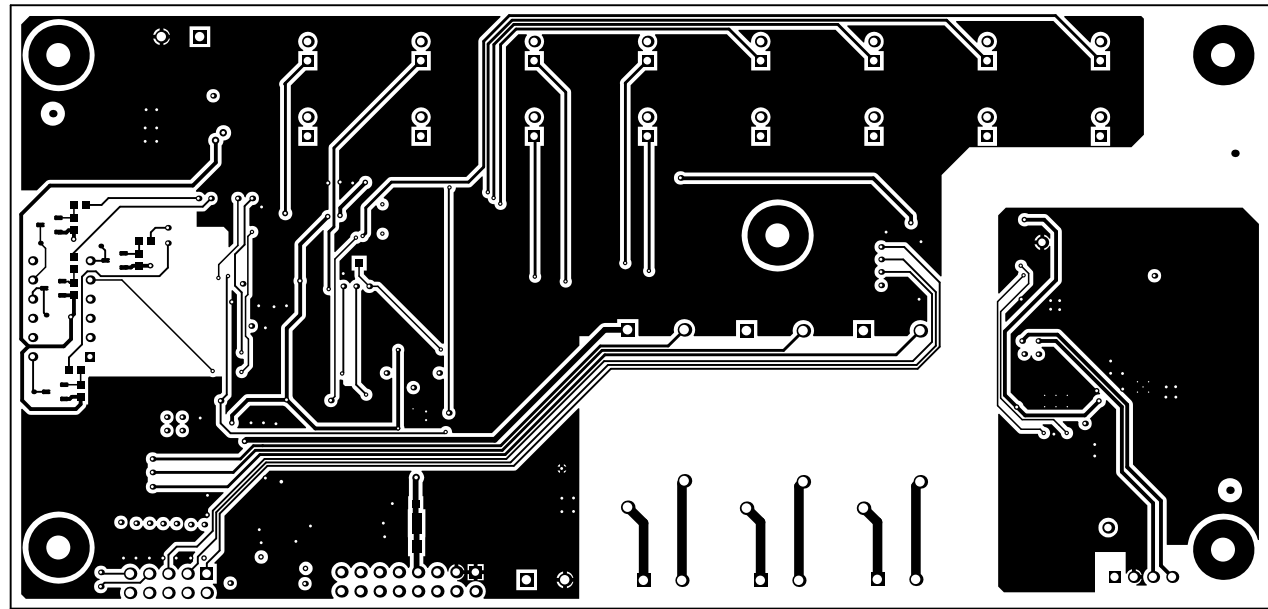
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00737	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 11/30/2015 4:21:06 PM	TEXAS INSTRUMENTS	



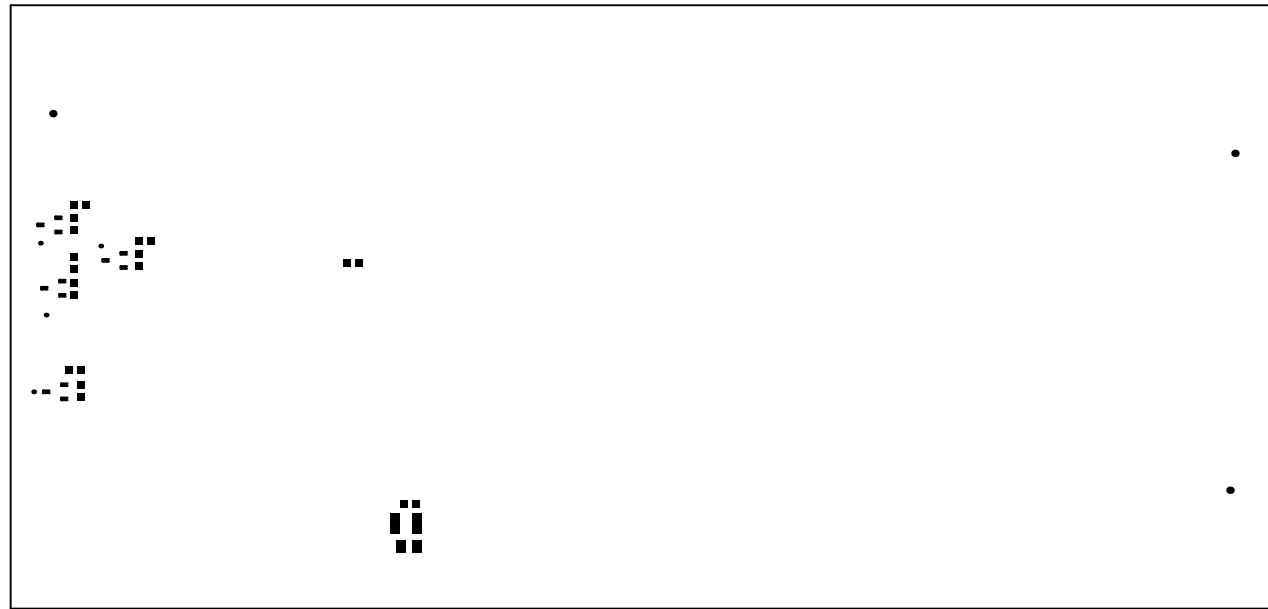
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LAYER NAME = Top Paste			
PLOT NAME = Top Paste	GENERATED : 11/30/2015 4:21:06 PM	TEXAS INSTRUMENTS	



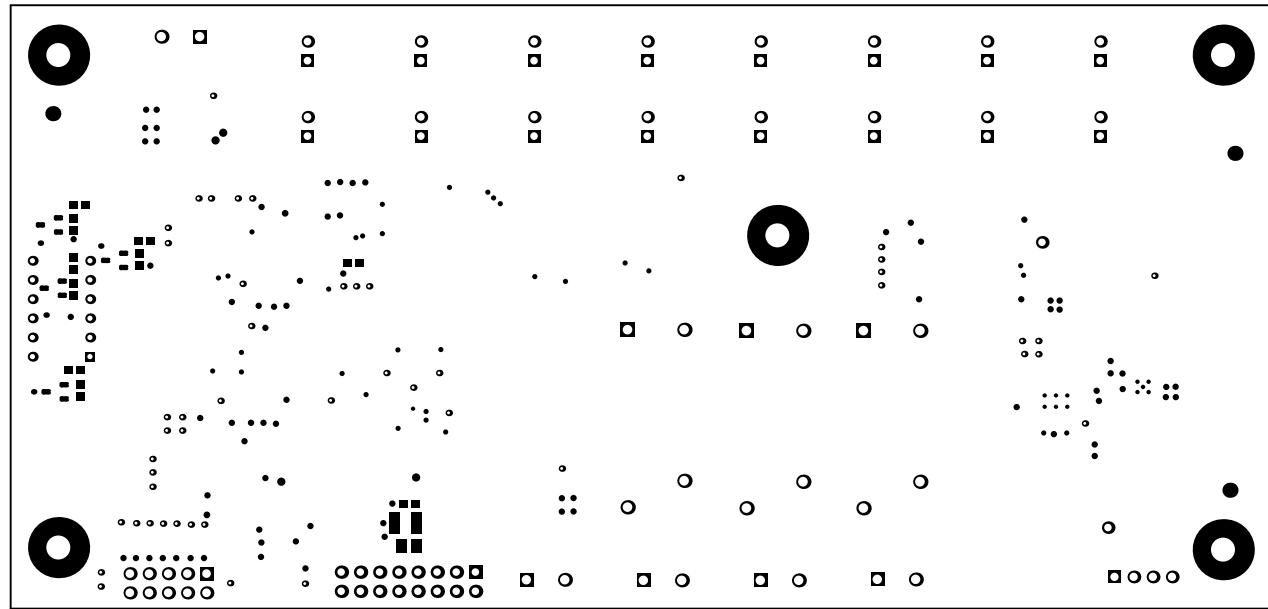
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00737	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 11/30/2015 4:21:06 PM	TEXAS INSTRUMENTS	



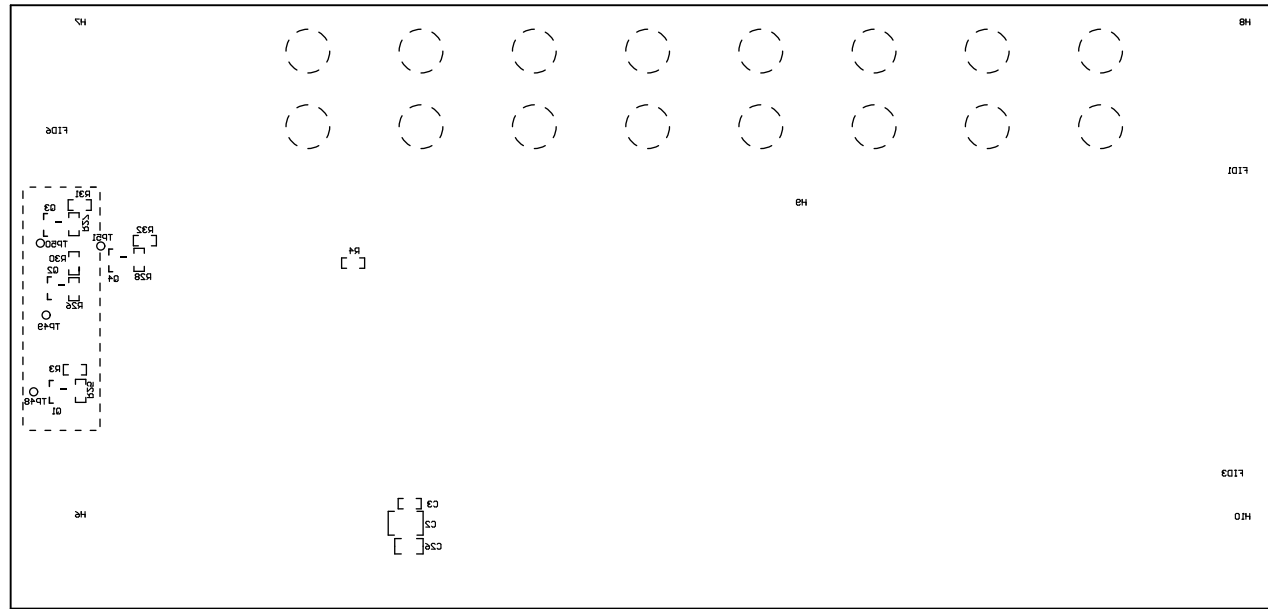
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00737	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 11/30/2015 4:21:07 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00737	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Paste			
PLOT NAME = Bottom paste	GENERATED : 11/30/2015 4:21:07 PM	TEXAS INSTRUMENTS	



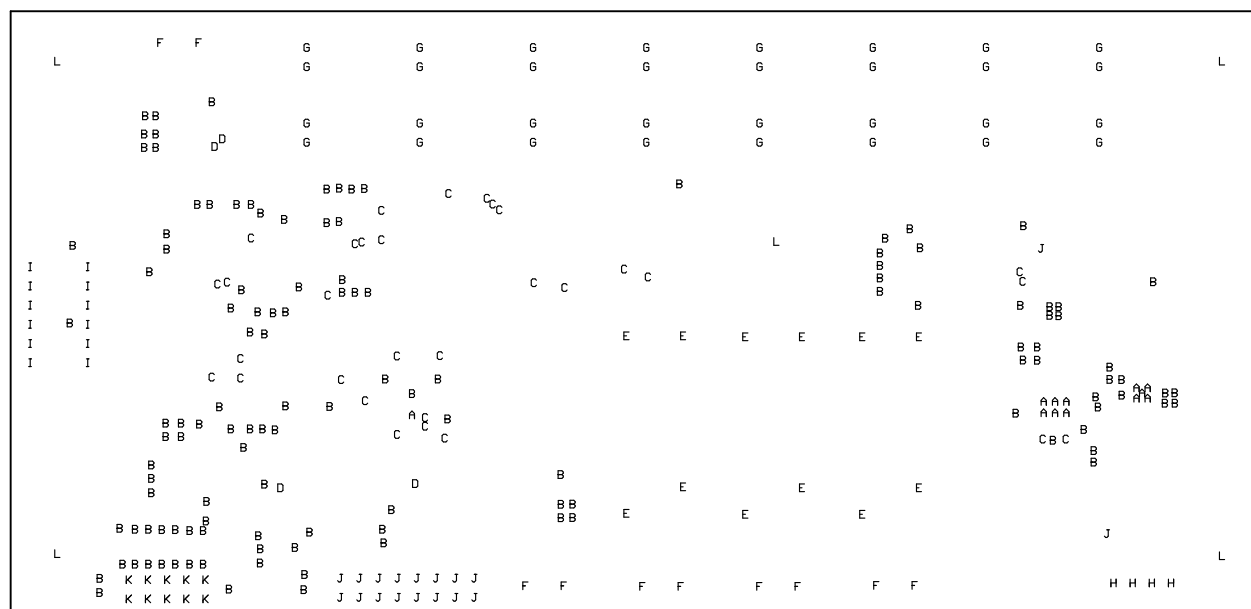
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00737	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 11/30/2015 4:21:07 PM	TEXAS INSTRUMENTS	



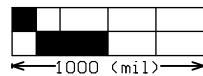
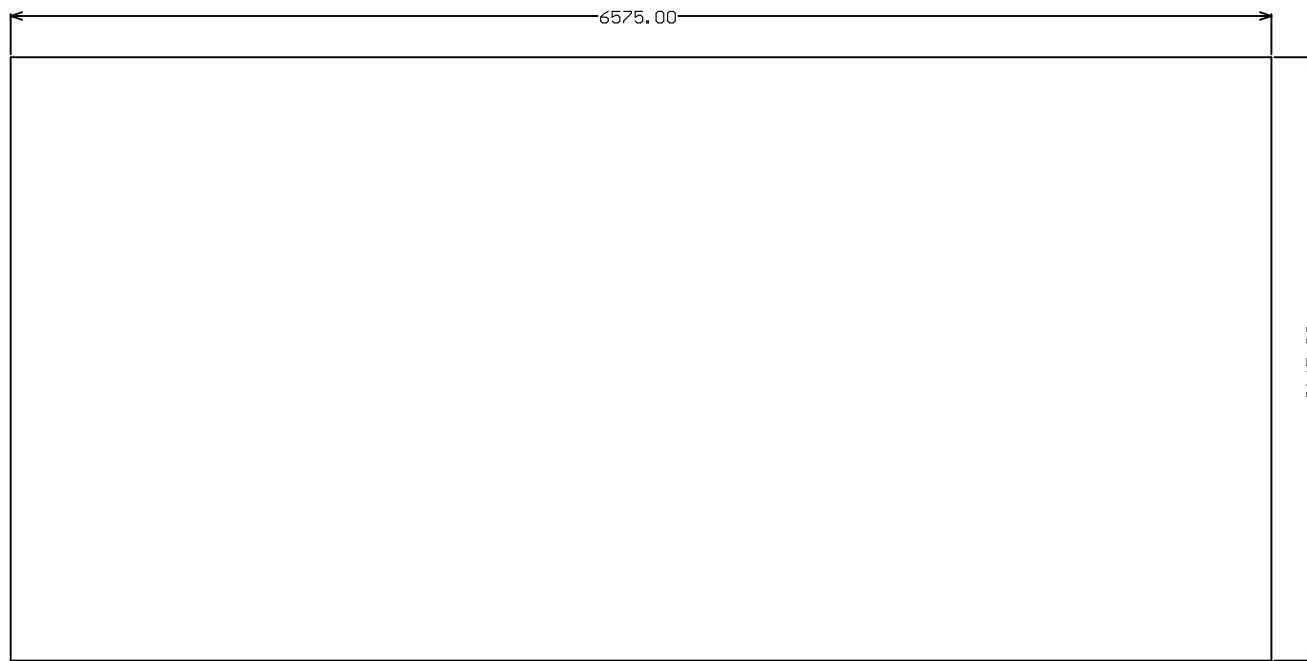
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00737	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 11/30/2015 4:21:07 PM	TEXAS INSTRUMENTS	

Symbol	Hit Count	Tool Size	Plated	Hole Type
A	12	7.874mil (0.2mm)	PTH	Round
C	31	12mil (0.305mm)	PTH	Round
B	126	16mil (0.406mm)	PTH	Round
D	4	20mil (0.508mm)	PTH	Round
I	12	28mil (0.711mm)	PTH	Round
J	18	40mil (1.016mm)	PTH	Round
G	32	40.945mil (1.04mm)	PTH	Round
H	4	43.307mil (1.1mm)	PTH	Round
K	10	45.276mil (1.15mm)	PTH	Round
F	10	49.213mil (1.25mm)	PTH	Round
E	12	51.181mil (1.3mm)	PTH	Round
L	5	125.984mil (3.2mm)	PTH	Round
	276 Total			

Drill Table
FOR 7.874MIL DRILL +0/-7.874MIL
FOR 12MIL DRILL +0/-12MIL
FOR 16MIL DRILL +0/-16MIL
FOR PTH DRILL +/-3MIL



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00737	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 11/30/2015 4:21:07 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00737	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Board Dimensions	GENERATED : 11/30/2015 4:21:08 PM	TEXAS INSTRUMENTS	

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